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EXAMINER

BAREFORD, KATHERINE A

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1792

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PAPER

Please find below and/or attached an Office communication concerning this application or proceeding.

The time period for reply, if any, is set in the attached communication.

Office Action Summary	Application No. 10/516,582	Applicant(s) BHANGALE ET AL.	
	Examiner Katherine A. Bareford	Art Unit 1792	

-- The MAILING DATE of this communication appears on the cover sheet with the correspondence address --

Period for Reply

A SHORTENED STATUTORY PERIOD FOR REPLY IS SET TO EXPIRE 3 MONTH(S) OR THIRTY (30) DAYS, WHICHEVER IS LONGER, FROM THE MAILING DATE OF THIS COMMUNICATION.

- Extensions of time may be available under the provisions of 37 CFR 1.136(a). In no event, however, may a reply be timely filed after SIX (6) MONTHS from the mailing date of this communication.
- If NO period for reply is specified above, the maximum statutory period will apply and will expire SIX (6) MONTHS from the mailing date of this communication.
- Failure to reply within the set or extended period for reply will, by statute, cause the application to become ABANDONED (35 U.S.C. § 133). Any reply received by the Office later than three months after the mailing date of this communication, even if timely filed, may reduce any earned patent term adjustment. See 37 CFR 1.704(b).

Status

- 1) ☐ Responsive to communication(s) filed on ____.
- 2a) ☐ This action is **FINAL**. 2b) ☒ This action is non-final.
- 3) ☐ Since this application is in condition for allowance except for formal matters, prosecution as to the merits is closed in accordance with the practice under *Ex parte Quayle*, 1935 C.D. 11, 453 O.G. 213.

Disposition of Claims

- 4) ☒ Claim(s) 1-29 is/are pending in the application.
- 4a) Of the above claim(s) ____ is/are withdrawn from consideration.
- 5) ☐ Claim(s) ____ is/are allowed.
- 6) ☒ Claim(s) 1-10, 12-27 and 29 is/are rejected.
- 7) ☐ Claim(s) ____ is/are objected to.
- 8) ☐ Claim(s) ____ are subject to restriction and/or election requirement.

Claims 11 and 28 are canceled

Application Papers

- 9) ☐ The specification is objected to by the Examiner.
- 10) ☐ The drawing(s) filed on ____ is/are: a) ☐ accepted or b) ☐ objected to by the Examiner.
Applicant may not request that any objection to the drawing(s) be held in abeyance. See 37 CFR 1.85(a).
Replacement drawing sheet(s) including the correction is required if the drawing(s) is objected to. See 37 CFR 1.121(d).
- 11) ☐ The oath or declaration is objected to by the Examiner. Note the attached Office Action or form PTO-152.

Priority under 35 U.S.C. § 119

- 12) ☒ Acknowledgment is made of a claim for foreign priority under 35 U.S.C. § 119(a)-(d) or (f).
- a) ☒ All b) ☐ Some * c) ☐ None of:
1. ☐ Certified copies of the priority documents have been received.
2. ☐ Certified copies of the priority documents have been received in Application No. ____.
3. ☒ Copies of the certified copies of the priority documents have been received in this National Stage application from the International Bureau (PCT Rule 17.2(a)).

* See the attached detailed Office action for a list of the certified copies not received.

Attachment(s)

- | | |
|---|--|
| 1) <input checked="" type="checkbox"/> Notice of References Cited (PTO-892) | 4) <input type="checkbox"/> Interview Summary (PTO-413)
Paper No(s)/Mail Date. ____ |
| 2) <input type="checkbox"/> Notice of Draftsperson's Patent Drawing Review (PTO-948) | 5) <input type="checkbox"/> Notice of Informal Patent Application |
| 3) <input checked="" type="checkbox"/> Information Disclosure Statement(s) (PTO/SB/08)
Paper No(s)/Mail Date <u>8/05</u> | 6) <input type="checkbox"/> Other: ____ |

DETAILED ACTION

1. The preliminary amendment filed December 2, 2004 has been received and entered. With the entry of the amendment, claims 11 and 28 have been canceled, and claims 1-10, 12-27 and 29 are pending for examination.

Claim Rejections - 35 USC § 103

2. The following is a quotation of 35 U.S.C. 103(a) which forms the basis for all obviousness rejections set forth in this Office action:

(a) A patent may not be obtained though the invention is not identically disclosed or described as set forth in section 102 of this title, if the differences between the subject matter sought to be patented and the prior art are such that the subject matter as a whole would have been obvious at the time the invention was made to a person having ordinary skill in the art to which said subject matter pertains. Patentability shall not be negated by the manner in which the invention was made.

3. This application currently names joint inventors. In considering patentability of the claims under 35 U.S.C. 103(a), the examiner presumes that the subject matter of the various claims was commonly owned at the time any inventions covered therein were made absent any evidence to the contrary. Applicant is advised of the obligation under 37 CFR 1.56 to point out the inventor and invention dates of each claim that was not commonly owned at the time a later invention was made in order for the examiner to consider the applicability of 35 U.S.C. 103(c) and potential 35 U.S.C. 102(e), (f) or (g) prior art under 35 U.S.C. 103(a).

4. Claims 1, 2, 5-10, 12, 15-17, 19, 22, 27 and 29 are rejected under 35 U.S.C. 103(a) as being unpatentable over Doany et al (US 7033648) in view of Boonekamp, et al

Art Unit: 1792

"Adsorption of Nanometer-Sized Palladium particles of Si(100) Surfaces" (hereinafter Boonekamp).

Claims 1, 29: Doany teaches a method of seeding (activating) and metallizing an aromatic polymer film in the form of polyimide. Column 2, lines 10-25 and column 6, line 45 through column 7, line 25. A first surface of the polyimide is pretreated with a basic (alkali) solution of metal hydroxide, such as sodium or potassium hydroxide. Column 5, line 65 through column 6, line 5 and column 6, line 65 through column 7, line 5. Following the pretreatment step, an aqueous seeding solution of catalyst such as palladium is applied to the first surface of the film. Column 7, lines 1-10. Then the film is immersed in an electroless plating bath comprising ions of a desired metal (such as copper) so as to deposit a layer of metal onto the first surface of the film. Column 7, lines 10-20. A resulting coated product is formed by the method. Column 7, lines 10-25.

Claim 2: the basic solution can be a solution of potassium hydroxide. Column 6, lines 1-2.

Claim 10: the desired metal can be copper. Column 7, lines 10-20.

Claim 12: the basic solution is applied by immersing the film in a bath of the basic solution. Column 6, lines 65-68.

Claim 17: the film is washed with water after catalyzing for 60 seconds. Column 7, lines 5-10.

Claim 19: the film is heated after depositing the electroless plating layer of metal. Column 7, lines 15-20.

Claim 22: prior to applying the basis solution, photoresist material is applied to the film and developed so as to assist patterning. Column 6, lines 50-65. This pattern can be used to form circuitry. Column 1, lines 20-25.

Claim 27: the polymer film is a polyimide. Column 2, lines 5-15.

Doany teaches all the features of these claims except (1) the use of polymer stabilized catalyst particles and their features (claims 1, 5-9, 29), (2) the immersion in the seeding solution and its time (claims 15, 16), (3) washing with deionized water (claim 17).

However, Boonekamp teaches the known replacement of palladium salt deposition for electroless plating activation with water stabilized palladium catalyst particles. Page 4089. The particles can be stabilized by a water soluble polymer, such as polyvinyl pyrrolidone (PVP). Page 4089. The palladium particles can have diameters of 15-25 nm. Page 4091. The palladium particles can be applied as a catalyst by immersing the substrate into a solution containing the particles. Page 4090. The contact can be for under one minute, for example. Page 4090, figure 1. Then the surface is rinsed under running water. Page 4090.

The Examiner takes Official Note that it is well known in the art of electroless plating to perform water rinsing/washing steps with deionized water. If applicant disagrees, he should so respond on the record.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Doany to use the water stabilized palladium catalyst

particles with the features taught by Boonekamp as the seeding catalyst with an expectation of desirable plating results, because Doany teaches to use, for example, appropriate palladium salt solutions (column 6, lines 10-15) for seeding for electroless plating and Boonekamp teaches a replacement for palladium salt solutions for seeding for electroless plating is to use water stabilized palladium catalyst particles, stabilized with PVP, for example and having a palladium particle size of 15-25 nm, and to apply the particles by immersion in a bath of the seeding solution for a period of time that can range from under one minute, and then to rinse the surface with water. As to the precise time of contact with the seeding solution, in the case where the claimed ranges "overlap or lie inside ranges disclosed by the prior art" a prima facie case of obviousness exists. In re Wertheim, 541 F.2d 257, 191 USPQ 90 (CCPA 1976), and here Boonekamp teaches contact times of under 1 minute. As to the use of deionized water, it is the Examiner's position that this would have been obvious to one of ordinary skill in the art for desirable plating results, because it is well known to be conventional to use deionized water in water rinsing/washing steps in electroless plating processes.

5. Claims 3, 4, 14 and 18 are rejected under 35 U.S.C. 103(a) as being unpatentable over Doany in view of Boonekamp as applied to claims 1, 2, 5-10, 12, 15-17, 19, 22, 27 and 29 above, and further in view of Fraenkel et al (US 4803097).

Doany in view of Boonekamp teach all the features of these claims except (1) the acid solution treatment and its material (claims 3, 4), (2) the time of contact with the

basic solution and washing off after contact (claim 14), (3) washing the applied metal layer after coating with deionized water and drying (claim 18).

Fraenkel teaches a method of activating and metallizing an aromatic polymer film such as a polyimide. Column 5, lines 35-60, column 1, lines 5-15 and column 13, lines 1-25. A first surface of the polymer is pretreated with a basic solution (conditioning solvent) of a material such as potassium hydroxide. Column 6, line 65 through column 7, line 25. Then a seeding solution of polymer catalyst is applied to the surface of the substrate. Column 13, lines 1-20. Then the substrate is immersed in an electroless plating bath. Column 12, lines 1-15 and column 13, lines 15-25. After the basic solution treatment, and before the catalyst treatment, an acid solution can be applied to the first surface. Column 8, lines 5-10. The acid solution can be a solution of hydrochloric acid. Column 8, lines 5-10. The time of contact with the basic solution can be 10 minutes. Column 12, lines 55-65. After treatment with the basic solution the samples are rinsed with water. Column 12, lines 55-65. After the electroless plating is applied, the coated article is rinsed with water. Column 13, lines 15-25. Heating can also occur after plating. Column 13, lines 45-50.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Doany in view of Boonekamp to provide a hydrochloric acid solution treatment between the basic solution treatment and the catalyst treatment as suggested by Fraenkel in order to provide desirable conditioning of the surface, because Doany in view of Boonekamp teaches a treatment process for electroless

Art Unit: 1792

plating with a basic solution treatment followed by a catalyst treatment, and Fraenkel teaches that when providing a basic solution treatment followed by a catalyst treatment, it is desirable to provide a hydrochloric acid solution treatment between the steps. It would further have been obvious to modify Doany in view of Boonekamp to provide a solution contact time of ten minutes, for example, and to wash after application as suggested by Fraenkel in order to provide desirable pretreatment, because Doany in view of Boonekamp teaches a basic solution pretreatment before electroless plating, and Fraenkel teaches that when providing a basic solution pretreatment before electroless plating, it is well known to have a solution contact time of ten minutes, for example, and to wash after application. It further would have been obvious to modify Doany in view of Boonekamp to provide washing and drying after plating as suggested by Fraenkel in order to provide desirable plating, because Doany in view of Boonekamp teaches to perform electroless plating, and Fraenkel teaches that it is well known to perform water rinsing (washing) after plating and heating which would provide drying. Furthermore, it would have been obvious for the water to be deionized, because as discussed in the rejection above, it is the Examiner's position that this would have been obvious to one of ordinary skill in the art for desirable plating results, because it is well known to be conventional to use deionized water in water rinsing/ washing steps in electroless plating processes.

6. Claim 13 is rejected under 35 U.S.C. 103(a) as being unpatentable over Doany in view of Boonekamp as applied to claims 1, 2, 5-10, 12, 15-17, 19, 22, 27 and 29 above, and further in view of Lake et al (US 4915983).

Doany in view of Boonekamp teach all the features of this claim except spraying the layer of basic solution onto the surface of the polymer.

Lake teaches a plating method for polyimide containing circuit boards, where a treatment with potassium hydroxide solution is provided. Column 9, lines 30-65. Lake teaches that such an application of potassium hydroxide solution can be performed by either spray or immersion. Column 99, lines 45-50.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Doany in view of Boonekamp to apply the basic solution by spraying as suggested by Lake in order to provide desirable conditioning of the surface, because Doany in view of Boonekamp teaches a treatment process for electroless plating with a basic solution treatment that is applied by immersion, and Lake teaches that when applying a basic solution treatment of potassium hydroxide, for example, either spray or immersion techniques can desirably be used.

7. Claims 3, 20 and 23 are rejected under 35 U.S.C. 103(a) as being unpatentable over Doany in view of Boonekamp as applied to claims 1, 2, 5-10, 12, 15-17, 19, 22, 27 and 29 above, and further in view of Walsh (US 5478462).

Doany in view of Boonekamp teach all the features of these claims except (1) the acid treatment (claim 3), (2) vias formed prior to applying the basic solution (claim 20) and (3) cleaning and drying the film prior to applying the basic solution (claim 23).

Doany teaches the desire to make circuits, etc. Column 1, lines 20-30.

Walsh teaches a method of activating and metallizing an aromatic polymer film such as a polyimide. Column 1, lines 20-30 and column 9, lines 50-65. A first surface of the polymer is pretreated with a basic solution of a material such as potassium hydroxide. Column 5, lines 15-30 and column 9, lines 10-50. Then a seeding solution of polymer catalyst is applied to the surface of the substrate. Column 9, lines 50-65. Then the substrate is immersed in an electroless plating bath. Column 13, lines 45-55. After the basic solution treatment, and before the catalyst treatment, an acid solution can be applied to the first surface. Column 13, lines 25-50. Prior to treatment the substrate can have vias formed. Column 7, lines 1-10 and column 14, lines 30-40. Prior to the step of applying the basic solution, the substrate can be cleaned. Column 9, lines 5-10.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Doany in view of Boonekamp to provide an acid solution treatment between the basic solution treatment and the catalyst treatment as suggested by Walsh in order to provide desirable pretreatment of the surface, because Doany in view of Boonekamp teaches a treatment process for electroless plating with a basic solution treatment followed by a catalyst treatment, and Walsh teaches that when providing a basic solution treatment followed by a catalyst treatment, it is desirable to

provide an acid solution treatment between the steps. It further would have been obvious to modify Doany in view of Boonekamp to provide vias formed in the substrate before treatment as suggested by Walsh in order to provide desirable circuit systems, because Doany in view of Boonekamp provides a treatment that can be for circuit systems, and Walsh teaches that when treating products used for such systems, it is well known to provide vias in the substrate before pretreatment and coating. It further would have been obvious to modify Doany in view of Boonekamp to provide that the substrate is cleaned and dried before coating as suggested by Walsh to provide a desirable surface for treatment, because Doany in view of Boonekamp provides pretreating a surface with basic solution, and Walsh teaches that before such treatment it is well known to clean the surface, and it would further have been obvious for the surface to be dried because if the surface is not cleaned a dried surface is started with, and therefore a dried surface is the standard starting point.

8. Claim 21 is rejected under 35 U.S.C. 103(a) as being unpatentable over Doany in view of Boonekamp and Walsh as applied to claims 3, 20 and 23 above, and further in view of Nuzzi et al (US 4425380).

Doany in view of Boonekamp and Walsh teach all the features of these claims except forming the vias by laser drilling.

Nuzzi teaches that when forming vias in substrates for circuit boards, it is well known to use laser drilling to form the holes. Column 1, lines 10-55.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Doany in view of Boonekamp and Walsh to form the vias by laser drilling as suggested by Nuzzi in order to provide desirable vias, because Doany in view of Boonekamp and Walsh teaches a treatment process for electroless plating for circuit boards with a substrate with preformed vias, and Nuzzi teaches that a well known way to form such vias is by laser drilling.

9. Claim 24 is rejected under 35 U.S.C. 103(a) as being unpatentable over Doany in view of Boonekamp and Walsh as applied to claims 3, 20 and 23 above, and further in view of Morgan (US 5543217).

Doany in view of Boonekamp and Walsh teach all the features of this claim except forming the cleaning by ultrasonication in acetone and deionized water. Boonekamp teaches cleaning the substrate ultrasonically in ethanol. Page 4090.

Morgan teaches that it is well known to clean polyimide substrates using acetone in an ultrasonic bath. Column 16, lines 50-55.

The Examiner takes Official Notice that adding water to acetone and other cleaning baths is a conventional way to control the concentration. If applicant disagrees, he should so respond on the record.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Doany in view of Boonekamp and Walsh to clean the substrate with acetone in an ultrasonic bath as suggested by Morgan in order to provide

Art Unit: 1792

a clean polyimide substrate, because Doany in view of Boonekamp and Walsh teaches a treatment process for electroless plating with a base of polyimide where precleaning can occur, and Morgan teaches that a well known way to clean polyimide is using acetone with ultrasonication. Furthermore, the use of water in the bath would be a conventional way to control the concentration of the bath for desirable control, and as to the use of deionized water, it is the Examiner's position that this would have been obvious to one of ordinary skill in the art for desirable plating results, because it is well known to be conventional to use deionized water in water use steps in electroless plating processes as previously discussed.

10. Claims 25 and 26 are rejected under 35 U.S.C. 103(a) as being unpatentable over Doany in view of Boonekamp, Walsh and Morgan as applied to claim 24 above, and further in view of Fraenkel et al (US 4425380).

Doany in view of Boonekamp, Walsh and Morgan teach all the features of these claims except ~~forming the vias by laser drilling~~ ^{the ozone cleaning}.

Fraenkel teaches a method of activating and metallizing an aromatic polymer film such as a polyimide. Column 5, lines 35-60, column 1, lines 5-15 and column 13, lines 1-25. A first surface of the polymer is pretreated with a basic solution (conditioning solvent) of a material such as potassium hydroxide. Column 6, line 65 through column 7, line 25. Then a seeding solution of polymer catalyst is applied to the surface of the substrate. Column 13, lines 1-20. Then the substrate is immersed in an

Art Unit: 1792

electroless plating bath. Column 12, lines 1-15 and column 13, lines 15-25. After the basic solution treatment, and before the catalyst treatment, an acid solution can be applied to the first surface. Column 8, lines 5-10. The acid solution can be a solution of hydrochloric acid. Column 8, lines 5-10. The time of contact with the basic solution can be 10 minutes. Column 12, lines 55-65. After treatment with the basic solution the samples are rinsed with water. Column 12, lines 55-65. After the electroless plating is applied, the coated article is rinsed with water. Column 13, lines 15-25. Heating can also occur after plating. Column 13, lines 45-50. Fraenkel further teaches that an ozone pretreatment is provided before the basic solution step, which provides etching (which would provide further "cleaning" as surfaces would be removed). Column 4, lines 50-65. The ozone temperature treatment can be elevated. Column 4, lines 35-45. The ozone treatment can be at between 50-110 degrees C for a time of 1-5 seconds to 1-2 hours. Column 4, line 35 through column 5, line 2.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Doany in view of Boonekamp, Walsh and Morgan to provide the ozone pretreatment as suggested by Fraenkel in order to provide desirable conditions for the pretreatment, because Doany in view of Boonekamp, Walsh and Morgan teaches a pretreatment process for electroless plating, and Fraenkel teaches that ⁱⁿ ~~is~~ such a pretreatment process it is desirable to perform ozone treatment before the application of a basic solution. Furthermore, as to the conditions of treatment, Fraenkel teaches temperatures and times overlapping that claimed, and in the case where the

claimed ranges "overlap or lie inside ranges disclosed by the prior art" a prima facie case of obviousness exists. In re Wertheim, 541 F.2d 257, 191 USPQ 90 (CCPA 1976).

11. Claims 1-10, 14-19, 27 and 29 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fraenkel et al (US 4803097) in view of Boonekamp, et al "Adsorption of Nanometer-Sized Palladium particles of Si(100) Surfaces" (hereinafter Boonekamp).

Claims 1, 29: Fraenkel teaches a method of activating and metallizing an aromatic polymer film such as a polyimide. Column 5, lines 35-60, column 1, lines 5-15 and column 13, lines 1-25. A first surface of the polymer is pretreated with a basic solution (conditioning solvent) of a material such as potassium hydroxide. Column 6, line 65 through column 7, line 25. Then a seeding solution of polymer catalyst is applied to the surface of the substrate. Column 13, lines 1-20. Then the substrate is immersed in an electroless plating bath to deposit a layer of metal onto the first surface. Column 12, lines 1-15 and column 13, lines 15-25. A coated product is formed by this method. Column 13, lines 1-50.

Claim 2: the basic solution can be potassium hydroxide. Column 7, lines 5-10.

Claims 3-4: After the basic solution treatment, and before the catalyst treatment, an acid solution can be applied to the first surface. Column 8, lines 5-10. The acid solution can be a solution of hydrochloric acid. Column 8, lines 5-10.

Claim 10: the metal to be plated can be copper or nickel. Column 13, lines 15-20.

Claim 14: The time of contact with the basic solution can be 10 minutes. Column 12, lines 55-65. After treatment with the basic solution the samples are rinsed with water. Column 12, lines 55-65.

Claim 15: the seeding solution is applied by immersion. Column 13, lines 1-15.

Claim 17: after application of the seeding solution, the film is washed with water. column 13, lines 5-20.

Claim 18: After the electroless plating is applied, the coated article is rinsed with water. Column 13, lines 15-25.

Claim 19: Heating can also occur after plating. Column 13, lines 45-50.

Claim 27: the polymer film can be polyimide. column 5, lines 35-60.

Fraenkel teaches all the features of these claims except (1) the use of polymer stabilized catalyst particles and their features (claims 1, 5-9, 29), (2) the immersion in the specific seeding solution and its time (claims 15, 16), (3) washing with deionized water (claim 17, 18).

However, Boonekamp teaches the known replacement of palladium salt deposition for electroless plating activation with water stabilized palladium catalyst particles. Page 4089. The particles can be stabilized by a water soluble polymer, such as polyvinyl pyrrolidone (PVP). Page 4089. The palladium particles can have diameters of 15-25 nm. Page 4091. The palladium particles can be applied as a catalyst by immersing the substrate into a solution containing the particles. Page 4090. The contact

can be for under one minute, for example. Page 4090, figure 1. Then the surface is rinsed under running water. Page 4090.

The Examiner takes Official Note that it is well known in the art of electroless plating to perform water rinsing/ washing steps with deionized water. If applicant disagrees, he should so respond on the record.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Fraenkel to use the water stabilized palladium catalyst particles with the features taught by Boonekamp as the seeding catalyst with an expectation of desirable plating results, because Fraenkel teaches to use, for example, appropriate conventional electroless plating procedures (column 12, lines 1-15) and palladium containing solutions (column 13, lines 1-10) for seeding for electroless plating and Boonekamp teaches a replacement for conventional palladium salt solutions for seeding for electroless plating is to use water stabilized palladium catalyst particles, stabilized with PVP, for example and having a palladium particle size of 15-25 nm, and to apply the particles by immersion in a bath of the seeding solution for a period of time that can range from under one minute, and then to rinse the surface with water. As to the precise time of contact with the seeding solution, in the case where the claimed ranges "overlap or lie inside ranges disclosed by the prior art" a prima facie case of obviousness exists. In re Wertheim, 541 F.2d 257, 191 USPQ 90 (CCPA 1976), and here Boonekamp teaches contact times of under 1 minute. As to the use of deionized water, it is the Examiner's position that this would have been obvious to one of ordinary skill

in the art for desirable plating results, because it is well known to be conventional to use deionized water in water rinsing/washing steps in electroless plating processes.

12. Claims 12 and 13 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fraenkel in view of Boonekamp as applied to claims 1-10, 14-19, 27 and 29 above, and further in view of Lake et al (US 4915983).

Fraenkel in view of Boonekamp teach all the features of these claims except immersing or spraying the layer of basic solution onto the surface of the polymer.

Lake teaches a plating method for polyimide containing circuit boards, where a treatment with potassium hydroxide solution is provided. Column 9, lines 30-65. Lake teaches that such an application of potassium hydroxide solution can be performed by either spray or immersion. Column 99, lines 45-50.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Fraenkel in view of Boonekamp to apply the basic solution by immersion or spraying as suggested by Lake in order to provide desirable conditioning of the surface, because Fraenkel in view of Boonekamp teaches a treatment process for electroless plating with a basic solution treatment that is applied to contact the substrate, and Lake teaches that when applying a basic solution treatment of potassium hydroxide, for example, either spray or immersion techniques can desirably be used.

13. Claims 20 and 23 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fraenkel in view of Boonekamp as applied to claims 1-10, 14-19, 27 and 29 above, and further in view of Walsh (US 5478462).

Fraenkel in view of Boonekamp teach all the features of these claims except (1) vias formed prior to applying the basic solution (claim 20) and (2) cleaning and drying the film prior to applying the basic solution (claim 23). Fraenkel teaches the desire to make circuits, etc. Column 3, lines 10-15.

Walsh teaches a method of activating and metallizing an aromatic polymer film such as a polyimide. Column 1, lines 20-30 and column 9, lines 50-65. A first surface of the polymer is pretreated with a basic solution of a material such as potassium hydroxide. Column 5, lines 15-30 and column 9, lines 10-50. Then a seeding solution of polymer catalyst is applied to the surface of the substrate. Column 9, lines 50-65. Then the substrate is immersed in an electroless plating bath. Column 13, lines 20-55. After the basic solution treatment, and before the catalyst treatment, an acid solution can be applied to the first surface. Column 13, lines 25-50. Prior to treatment the substrate can have vias formed. Column 7, lines 1-10 and column 14, lines 30-40. Prior to the step of applying the basic solution, the substrate can be cleaned. Column 9, lines 5-10.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Fraenkel in view of Boonekamp to provide vias formed in the substrate before treatment as suggested by Walsh in order to provide desirable circuit systems, because Fraenkel in view of Boonekamp provides a treatment that can

be for circuit systems, and Walsh teaches that when treating products used for such systems, it is well known to provide vias in the substrate before pretreatment and coating. It further would have been obvious to modify Fraenkel in view of Boonekamp to provide that the substrate is cleaned and dried before coating as suggested by Walsh to provide a desirable surface for treatment, because Fraenkel in view of Boonekamp provides pretreating a surface with basic solution, and Walsh teaches that before such treatment it is well known to clean the surface, and it would further have been obvious for the surface to be dried because if the surface is not cleaned a dried surface is started with, and therefore a dried surface is the standard starting point.

14. Claim 21 is rejected under 35 U.S.C. 103(a) as being unpatentable over Fraenkel in view of Boonekamp and Walsh as applied to claims 20 and 23 above, and further in view of Nuzzi et al (US 4425380).

Fraenkel in view of Boonekamp and Walsh teach all the features of this claim except forming the vias by laser drilling.

Nuzzi teaches that when forming vias in substrates for circuit boards, it is well known to use laser drilling to form the holes. Column 1, lines 10-55.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Fraenkel in view of Boonekamp and Walsh to form the vias by laser drilling as suggested by Nuzzi in order to provide desirable vias, because Fraenkel in view of Boonekamp and Walsh teaches a treatment process for electroless

plating for circuit boards with a substrate with preformed vias, and Nuzzi teaches that a well known way to form such vias is by laser drilling.

15. Claims 24-26 are rejected under 35 U.S.C. 103(a) as being unpatentable over Fraenkel in view of Boonekamp and Walsh as applied to claims 20 and 23 above, and further in view of Morgan (US 5543217).

Doany in view of Boonekamp and Walsh teach all the features of these claims except forming the cleaning by ultrasonication in acetone and deionized water.

Boonekamp teaches cleaning the substrate ultrasonically in ethanol. Page 4090. Fraenkel further teaches that an ozone pretreatment is provided before the basic solution step, which provides etching (which would provide further "cleaning" as surfaces would be removed). Column 4, lines 50-65. The ozone temperature treatment can be elevated. Column 4, lines 35-45. The ozone treatment can be at between 50-110 degrees C for a time of 1-5 seconds to 1-2 hours. Column 4, line 35 through column 5, line 2.

Morgan teaches that it is well known to clean polyimide substrates using acetone in an ultrasonic bath. Column 16, lines 50-55.

The Examiner takes Official Notice that adding water to acetone and other cleaning baths is a conventional way to control the concentration. If applicant disagrees, he should so respond on the record.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Fraenkel in view of Boonekamp and Walsh to clean the

substrate with acetone in an ultrasonic bath as suggested by Morgan in order to provide a clean polyimide substrate, because Fraenkel in view of Boonekamp and Walsh teaches a treatment process for electroless plating with a base of polyimide where precleaning can occur, and Morgan teaches that a well known way to clean polyimide is using acetone with ultrasonication. Furthermore, the use of water in the bath would be a conventional way to control the concentration of the bath for desirable control, and as to the use of deionized water, it is the Examiner's position that this would have been obvious to one of ordinary skill in the art for desirable plating results, because it is well known to be conventional to use deionized water in water use steps in electroless plating processes as previously discussed.

16. Claims 1-3, 5-10, 12, 14-17, 19-20, 23, 27 and 29 are rejected under 35 U.S.C. 103(a) as being unpatentable over Walsh (US 5478462) in view of Boonekamp, et al "Adsorption of Nanometer-Sized Palladium particles of Si(100) Surfaces" (hereinafter Boonekamp).

Claims 1, 29: Walsh teaches a method of activating and metallizing an aromatic polymer film such as a polyimide. Column 1, lines 20-30 and column 9, lines 50-65. A first surface of the polymer is pretreated with a basic solution of a material such as potassium hydroxide. Column 5, lines 15-30 and column 9, lines 10-50. Then a seeding solution of polymer catalyst is applied to the surface of the substrate. Column 9, lines 50-65. Then the substrate is immersed in an electroless plating bath to deposit a layer of

metal. Column 13, lines 20-55. A coated product is formed by the method. Column 13, lines 45-55.

Claim 2: the basic solution can be potassium hydroxide. Column 9, lines 18-25.

Claims 3: After the basic solution treatment, and before the catalyst treatment, an acid solution can be applied to the first surface. Column 13, lines 25-50.

Claim 10: the metal to be plated can be nickel. Column 13, lines 45-55.

Claim 12: the basic solution is applied by immersing the film in a bath of the solution. Column 13, lines 20-40.

Claim 14: The time of contact with the basic solution can be 1 minute. Column 13, lines 25-35. After treatment with the basic solution the samples are treated with acid which would wash the basic solution off. Column 13, lines 35-40.

Claim 15: the seeding solution is applied by immersion. Column 13, lines 40-45.

Claim 17: after application of the seeding solution, the film is washed with water. Column 13, lines 40-50.

Claim 19: Heating can also occur after plating. Column 13, lines 55-60.

Claim 20: Prior to treatment the substrate can have vias formed. Column 7, lines 1-10 and column 14, lines 30-40.

Claim 23: Prior to the step of applying the basic solution, the substrate can be cleaned. Column 9, lines 5-10.

Claim 27: the polymer film can be polyimide. Column 13, lines 20-25.

Walsh teaches all the features of these claims except (1) the use of polymer stabilized catalyst particles and their features (claims 1, 5-9, 29), (2) the immersion in the specific seeding solution and its time (claims 15, 16), (3) washing with deionized water (claim 17, 18).

However, Boonekamp teaches the known replacement of palladium salt deposition for electroless plating activation with water stabilized palladium catalyst particles. Page 4089. The particles can be stabilized by a water soluble polymer, such as polyvinyl pyrrolidone (PVP). Page 4089. The palladium particles can have diameters of 15-25 nm. Page 4091. The palladium particles can be applied as a catalyst by immersing the substrate into a solution containing the particles. Page 4090. The contact can be for under one minute, for example. Page 4090, figure 1. Then the surface is rinsed under running water. Page 4090.

The Examiner takes Official Note that it is well known in the art of electroless plating to perform water rinsing/washing steps with deionized water. If applicant disagrees, he should so respond on the record.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Walsh to use the water stabilized palladium catalyst particles with the features taught by Boonekamp as the seeding catalyst with an expectation of desirable plating results, because Walsh teaches to use, for example, appropriate conventional palladium containing solutions (column 13, lines 40-45) for seeding for electroless plating and Boonekamp teaches a replacement for conventional

Art Unit: 1792

palladium salt solutions for seeding for electroless plating is to use water stabilized palladium catalyst particles, stabilized with PVP, for example and having a palladium particle size of 15-25 nm, and to apply the particles by immersion in a bath of the seeding solution for a period of time that can range from under one minute, and then to rinse the surface with water. As to the precise time of contact with the seeding solution, in the case where the claimed ranges "overlap or lie inside ranges disclosed by the prior art" a prima facie case of obviousness exists. In re Wertheim, 541 F.2d 257, 191 USPQ 90 (CCPA 1976), and here Boonekamp teaches contact times of under 1 minute. As to the use of deionized water, it is the Examiner's position that this would have been obvious to one of ordinary skill in the art for desirable plating results, because it is well known to be conventional to use deionized water in water rinsing/washing steps in electroless plating processes.

17. Claims 4 and 18 are rejected under 35 U.S.C. 103(a) as being unpatentable over Walsh in view of Boonekamp as applied to claims 1-3, 5-10, 12, 14-17, 19-20, 23, 27 and 29 above, and further in view of Fraenkel et al (US 4803097).

Walsh in view of Boonekamp teach all the features of these claims except (1) the hydrochloric acid solution treatment (claim 4), (2) washing the applied metal layer after coating with deionized water and drying (claim 18).

Fraenkel teaches a method of activating and metallizing an aromatic polymer film such as a polyimide. Column 5, lines 35-60, column 1, lines 5-15 and column 13,

lines 1-25. A first surface of the polymer is pretreated with a basic solution (conditioning solvent) of a material such as potassium hydroxide. Column 6, line 65 through column 7, line 25. Then a seeding solution of polymer catalyst is applied to the surface of the substrate. Column 13, lines 1-20. Then the substrate is immersed in an electroless plating bath. Column 12, lines 1-15 and column 13, lines 15-25. After the basic solution treatment, and before the catalyst treatment, an acid solution can be applied to the first surface. Column 8, lines 5-10. The acid solution can be a solution of hydrochloric acid. Column 8, lines 5-10. The time of contact with the basic solution can be 10 minutes. Column 12, lines 55-65. After treatment with the basic solution the samples are rinsed with water. Column 12, lines 55-65. After the electroless plating is applied, the coated article is rinsed with water. Column 13, lines 15-25. Heating can also occur after plating. Column 13, lines 45-50.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Walsh in view of Boonekamp to provide a hydrochloric acid solution treatment between the basic solution treatment and the catalyst treatment as suggested by Fraenkel in order to provide desirable conditioning of the surface, because Walsh in view of Boonekamp teaches a treatment process for electroless plating with a basic solution treatment followed by a catalyst treatment with an acid treatment between, and Fraenkel teaches that when providing a basic solution treatment followed by a catalyst treatment, it is desirable to provide a hydrochloric acid solution treatment between the steps. It further would have been obvious to modify Walsh in view of

Art Unit: 1792

Boonekamp to provide washing and drying after plating as suggested by Fraenkel in order to provide desirable plating, because Walsh in view of Boonekamp teaches to perform electroless plating, and Fraenkel teaches that it is well known to perform water rinsing (washing) after plating and heating which would provide drying. Furthermore, it would have been obvious for the water to be deionized, because as discussed in the rejection above, it is the Examiner's position that this would have been obvious to one of ordinary skill in the art for desirable plating results, because it is well known to be conventional to use deionized water in water rinsing/washing steps in electroless plating processes.

18. Claim 13 is rejected under 35 U.S.C. 103(a) as being unpatentable over Walsh in view of Boonekamp as applied to claims 1-3, 5-10, 12, 14-17, 19-20, 23, 27 and 29 above, and further in view of Lake et al (US 4915983).

Walsh in view of Boonekamp teach all the features of this claim except spraying the layer of basic solution onto the surface of the polymer.

Lake teaches a plating method for polyimide containing circuit boards, where a treatment with potassium hydroxide solution is provided. Column 9, lines 30-65. Lake teaches that such an application of potassium hydroxide solution can be performed by either spray or immersion. Column 99, lines 45-50.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Walsh in view of Boonekamp to apply the basic solution

by spraying as suggested by Lake in order to provide desirable conditioning of the surface, because Walsh in view of Boonekamp teaches a treatment process for electroless plating with a basic solution treatment that is applied by immersion, and Lake teaches that when applying a basic solution treatment of potassium hydroxide, for example, either spray or immersion techniques can desirably be used.

19. Claim 21 is rejected under 35 U.S.C. 103(a) as being unpatentable over Walsh in view of Boonekamp as applied to claims 1-3, 5-10, 12, 14-17, 19-20, 23, 27 and 29 above, and further in view of Nuzzi et al (US 4425380).

Walsh in view of Boonekamp teach all the features of this claim except forming the vias by laser drilling.

Nuzzi teaches that when forming vias in substrates for circuit boards, it is well known to use laser drilling to form the holes. Column 1, lines 10-55.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Walsh in view of Boonekamp to form the vias by laser drilling as suggested by Nuzzi in order to provide desirable vias, because Walsh in view of Boonekamp teaches a treatment process for electroless plating for circuit boards with a substrate with preformed vias, and Nuzzi teaches that a well known way to form such vias is by laser drilling.

20. Claim 24 is rejected under 35 U.S.C. 103(a) as being unpatentable over Walsh in view of Boonekamp as applied to claims 1-3, 5-10, 12, 14-17, 19-20, 23, 27 and 29 above, and further in view of Morgan (US 5543217).

Walsh in view of Boonekamp teach all the features of this claim except forming the cleaning by ultrasonication in acetone and deionized water. Boonekamp teaches cleaning the substrate ultrasonically in ethanol. Page 4090.

Morgan teaches that it is well known to clean polyimide substrates using acetone in an ultrasonic bath. Column 16, lines 50-55.

The Examiner takes Official Notice that adding water to acetone and other cleaning baths is a conventional way to control the concentration. If applicant disagrees, he should so respond on the record.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Walsh in view of Boonekamp to clean the substrate with acetone in an ultrasonic bath as suggested by Morgan in order to provide a clean polyimide substrate, because Walsh in view of Boonekamp teaches a treatment process for electroless plating with a base of polyimide where precleaning can occur, and Morgan teaches that a well known way to clean polyimide is using acetone with ultrasonication. Furthermore, the use of water in the bath would be a conventional way to control the concentration of the bath for desirable control, and as to the use of deionized water, it is the Examiner's position that this would have been obvious to one of ordinary skill in the art for desirable plating results, because it is well known to be

conventional to use deionized water in water use steps in electroless plating processes as previously discussed.

21. Claims 25 and 26 are rejected under 35 U.S.C. 103(a) as being unpatentable over Walsh in view of Boonekamp and Morgan as applied to claim 24 above, and further in view of Fraenkel et al (US 4425380).

Walsh in view of Boonekamp and Morgan teach all the features of these claims except ^{the ozone cleaning} ~~forming the vias by laser drilling~~.

Fraenkel teaches a method of activating and metallizing an aromatic polymer film such as a polyimide. Column 5, lines 35-60, column 1, lines 5-15 and column 13, lines 1-25. A first surface of the polymer is pretreated with a basic solution (conditioning solvent) of a material such as potassium hydroxide. Column 6, line 65 through column 7, line 25. Then a seeding solution of polymer catalyst is applied to the surface of the substrate. Column 13, lines 1-20. Then the substrate is immersed in an electroless plating bath. Column 12, lines 1-15 and column 13, lines 15-25. After the basic solution treatment, and before the catalyst treatment, an acid solution can be applied to the first surface. Column 8, lines 5-10. The acid solution can be a solution of hydrochloric acid. Column 8, lines 5-10. The time of contact with the basic solution can be 10 minutes. Column 12, lines 55-65. After treatment with the basic solution the samples are rinsed with water. Column 12, lines 55-65. After the electroless plating is applied, the coated article is rinsed with water. Column 13, lines 15-25. Heating can

also occur after plating. Column 13, lines 45-50. Fraenkel further teaches that an ozone pretreatment is provided before the basic solution step, which provides etching (which would provide further "cleaning" as surfaces would be removed). Column 4, lines 50-65. The ozone temperature treatment can be elevated. Column 4, lines 35-45. The ozone treatment can be at between 50-110 degrees C for a time of 1-5 seconds to 1-2 hours. Column 4, line 35 through column 5, line 2.

It would have been obvious to one of ordinary skill in the art at the time the invention was made to modify Walsh in view of Boonekamp and Morgan to provide the ozone pretreatment as suggested by Fraenkel in order to provide desirable conditions for the pretreatment, because Walsh in view of Boonekamp and Morgan teaches a pretreatment process for electroless plating, and Fraenkel teaches that ⁱⁿ such a pretreatment process it is desirable to perform ozone treatment before the application of a basic solution. Furthermore, as to the conditions of treatment, Fraenkel teaches temperatures and times overlapping that claimed, and in the case where the claimed ranges "overlap or lie inside ranges disclosed by the prior art" a prima facie case of obviousness exists. In re Wertheim, 541 F.2d 257, 191 USPQ 90 (CCPA 1976).

22. The Examiner notes that the Boonekamp et al reference was provided by applicant with the IDS statement of August 29, 2005.


Conclusion

Any inquiry concerning this communication or earlier communications from the examiner should be directed to Katherine A. Bareford whose telephone number is (571) 272-1413. The examiner can normally be reached on M-F(6:00-3:30) with the First Friday Off.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's supervisor, Timothy Meeks can be reached on (571) 272-1423. The fax phone numbers for the organization where this application or proceeding is assigned are (571) 273-8300 for regular communications and for After Final communications.

Other inquiries can be directed to the Tech Center 1700 telephone number at (571) 272-1700.

Furthermore, information regarding the status of an application may be obtained from the Patent Application Information Retrieval (PAIR) system. Status information for published applications may be obtained from either Private PAIR or Public PAIR. Status information for unpublished applications is available through Private PAIR only. For more information about the PAIR system, see <http://pair-direct.uspto.gov>. Should you have questions on access to the Private PAIR system, contact the Electronic Business Center (EBC) at 866-217-9197 (toll-free).


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PRIMARY EXAMINER